

On page 11, in the fourth paragraph, please replace the current paragraph with the following:

-- During step 803 and FIG. 9(C), resin sealing of each semiconductor chip 90 is carried out by means of a mold 94. This molding step uses a mold having cavities (i.e. three cavities) corresponding to the regions of blocks 24A through 24C (refer to FIG. 4 and FIG. 6) demarcated by main line 20. Molding compound fed to the mold flows through runners (each cavity in this working example is provided with two runners) into each cavity, and multiple semiconductor chips 90 placed within these blocks are covered simultaneously. The region upon insulation film 10 covered by mold 94 includes the above mentioned sub-line 22 of the conductor pattern. Moreover, the above mentioned main line 20 of conductor pattern 18 may be partially or entirely included.—

On page 12, in the third paragraph, please replace the current paragraph with the following:

-- As described above, multiple semiconductor packages 102 are produced simultaneously using the above mentioned insulation film 10. During the above mentioned manufacturing, most of the region enclosed by main line 20 of the conductor pattern upon insulation film 10 (with the exceptions of the region of sub-line 22 removed by dicing and the region adjacent to main line 20) is used as a region of the substrate of the semiconductor package. The region of discarded insulation film becomes extremely small.—

In the Abstract:

Please replace the current Abstract with the following:

-- An insulation film for providing an insulation substrate carrying a semiconductor chip of a semiconductor package. Insulation film 10 is provided